CLAIMS:

1. A heat conductive silicone composition comprising

(a) 100 parts by weight of an organopolysiloxane having alkenyl groups only at both ends of a molecular chain,

(b) 200 to 3,000 parts by weight of a heat conductive filler,

(c) an organohydrogenpolysiloxane having hydrogen atoms directly bonded to silicon atoms (Si-H groups) only at both ends of a molecular chain, in such an amount that 0.1 to 5 moles of Si-H groups are available per mole of alkenyl groups in component (a), and

(d) a platinum group base curing catalyst in an amount to give 0.1 to 500 ppm of platinum group element based on the weight of component (a).

2. The composition of claim 1 wherein the heat conductive filler is selected from the group consisting of metals, oxides, nitrides, silicides, artificial diamond and mixtures thereof.

3. A heat conductive silicone article obtained by shaping the composition of claim 1 into a sheet.

4. A heat conductive silicone article shaped by applying the composition of claim 1 onto a heat dissipating sheet.